

Features

- High-speed access times
Com'l: 10, 12, 15 and 20ns
Ind'l: 12, 15 and 20ns
- Low power operation (typical)
 - PDM31256SA
 - Active: 200 mW
 - Standby: 15mW
- Single +3.3V ($\pm 0.3V$) power supply
- TTL-compatible inputs and outputs
- Packages
 - Plastic SOJ (300 mil) - SO
 - Plastic TSOP (I) - T

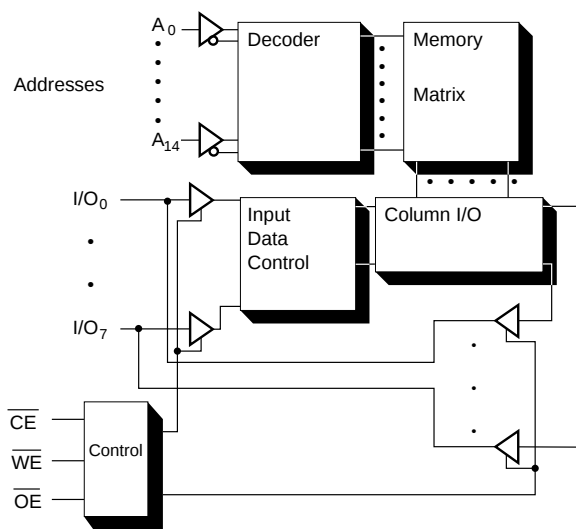
Description

The PDM31256 is a high-performance CMOS static RAM organized as 32,768 x 8 bits. Writing to this device is accomplished when the write enable ($\overline{WE}$) and the chip enable ($\overline{CE}$) inputs are both LOW. Reading is accomplished when $\overline{WE}$ remains HIGH and $\overline{CE}$ and $\overline{OE}$ are both LOW.

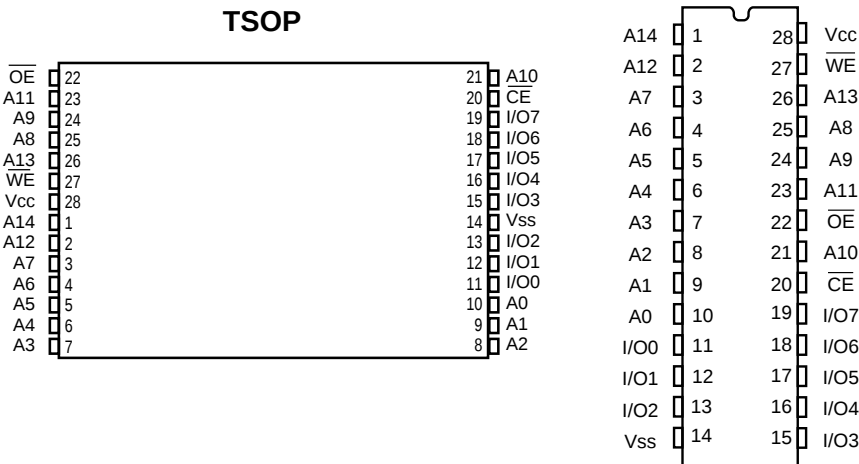
The PDM31256 operates from a single +3.3V power supply and all the inputs and outputs are fully TTL-compatible.

The PDM31256 is available in a 28-pin 300-mil plastic SOJ and a 28-pin plastic TSOP (I).

Functional Block Diagram



Pin Configurations



Pin Description

Name	Description
A14-A0	Address Inputs
I/O7-I/O0	Data Inputs/Outputs
OE	Output Enable Input
WE	Write Enable Input
CE	Chip Enable Input
V _{CC}	Power (+3.3V)
V _{SS}	Ground

Truth Table

OE	WE	CE	I/O	MODE
X	X	H	Hi-Z	Standby
L	H	L	D _{OUT}	Read
X	L	L	D _{IN}	Write
H	H	L	Hi-Z	Output Disable

NOTE: 1. H = V_{IH}, L = V_{IL}, X = DON'T CARE

Absolute Maximum Ratings ⁽¹⁾

Symbol	Rating	Com'l.	Ind.	Unit
V _{TERM}	Terminal Voltage with Respect to Vss	-0.5 to +4.6	-0.5 to +4.6	V
T _{BIAS}	Temperature Under Bias	-55 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +150	°C
P _T	Power Dissipation	1.0	1.0	W
I _{OUT}	DC Output Current	50	50	mA
T _j	Maximum Junction Temperature ⁽²⁾	125	145	°C

- NOTE: 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Appropriate thermal calculations should be performed in all cases and specifically for those where the chosen package has a large thermal resistance (e.g., TSOP). The calculation should be of the form: $T_j = T_a + P * \theta_{ja}$ where T_a is the ambient temperature, P is average operating power and θ_{ja} the thermal resistance of the package. For this product, use the following θ_{ja} values:

SOJ: 78 °C/W
TSOP: 112 °C/W

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{CC}	Supply Voltage	3.0	3.3	3.6	V
V _{SS}	Supply Voltage	0	0	0	V
Commercial	Ambient Temperature	0	25	70	°C
Industrial	Ambient Temperature	-40	25	85	°C

DC Electrical Characteristics (V_{CC} = 3.3V ± 0.3V)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
I _{LI}	Input Leakage Current	V _{CC} = MAX., V _{IN} = V _{SS} to V _{CC}	-5	5	μA
I _{LO}	Output Leakage Current	V _{CC} = MAX., CE = V _{IH} , V _{OUT} = V _{SS} to V _{CC}	-5	5	μA
V _{IL}	Input Low Voltage		-0.3 ⁽¹⁾	0.8	V
V _{IH}	Input High Voltage		2.2	V _{CC} +0.3	V
V _{OL}	Output Low Voltage	I _{OL} = 8 mA V _{CC} = Min.	—	0.4	V
V _{OH}	Output High Voltage	I _{OH} = -4 mA, V _{CC} = Min.	2.4	—	V

NOTE: 1. V_{IL}(min) = -3.0V for pulse width less than 20 ns.

Power Supply Characteristics

Symbol	Parameter	-10	-12		-15		-17		-20		Unit
		Com'l.	Com'l.	Ind.	Com'l.	Ind.	Com'l.	Ind.	Com'l.	Ind.	
I _{CC}	Operating Current CE = V _{IL} f = f _{MAX} = 1/t _{RC} V _{CC} = Max. I _{OUT} = 0 mA	140	130	130	120	120	120	120	110	110	mA
I _{SB}	Standby Current CE = V _{IH} f = f _{MAX} = 1/t _{RC} V _{CC} = Max.	45	40	35	35	35	35	35	30	30	mA
I _{SB1}	Full Standby Current CE ≥ V _{CC} - 0.2V f = 0 V _{CC} = Max., V _{IN} ≥ V _{CC} - 0.2V or ≤ 0.2V	10	10	15	10	15	10	15	10	15	mA

NOTES: All values are maximum guaranteed values.

Capacitance⁽¹⁾ ($T_A = +25^\circ\text{C}$, $f = 1.0\text{ MHz}$)

Symbol	Parameter	Max.	Unit
C_{IN}	Input Capacitance	8	pF
C_{OUT}	Output Capacitance	8	pF

NOTE: 1. This parameter is determined by device characterization but is not production tested.

AC Test Conditions

Input pulse levels	V_{SS} to 3.0V
Input rise and fall times	2.5 ns
Input timing reference levels	1.5V
Output reference levels	1.5V
Output load	See Figures 1 and 2

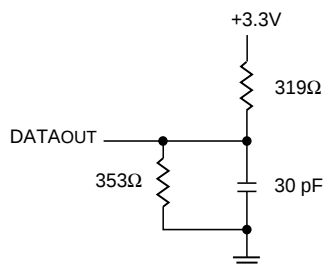


Figure 1. Output Load Equivalent

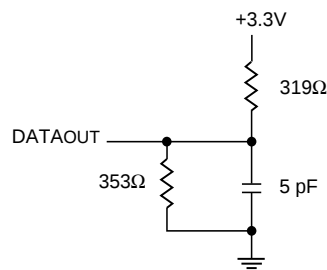


Figure 2. Output Load Equivalent
(for t_{LZCE} , t_{HZCE} , t_{LZWE} , t_{HZWE} , t_{LZOE} ,
 t_{HZOE})

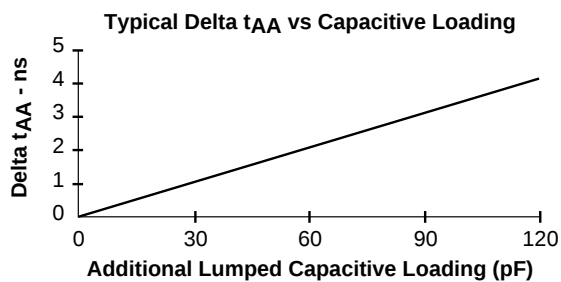
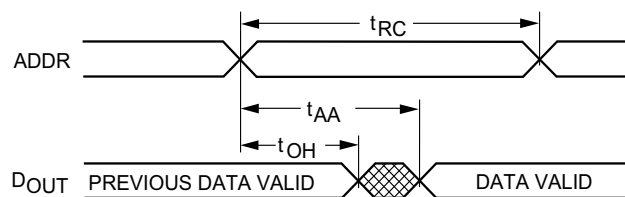
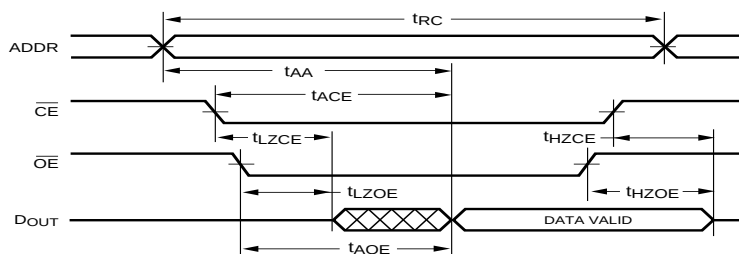


Figure 3.

Read Cycle No. 1⁽¹⁾

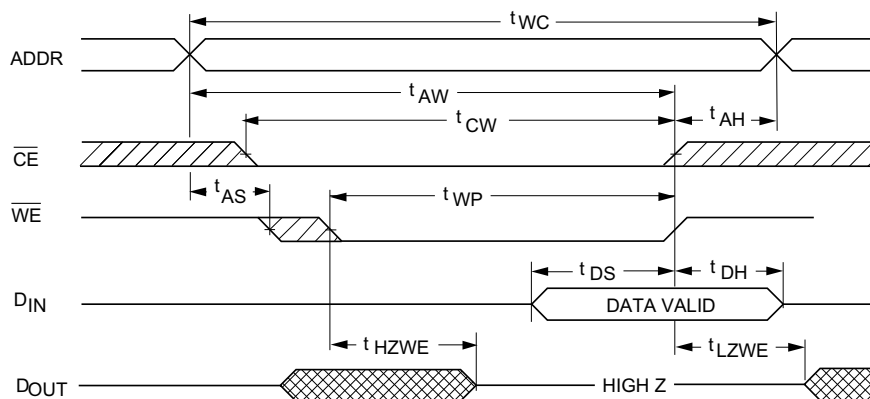
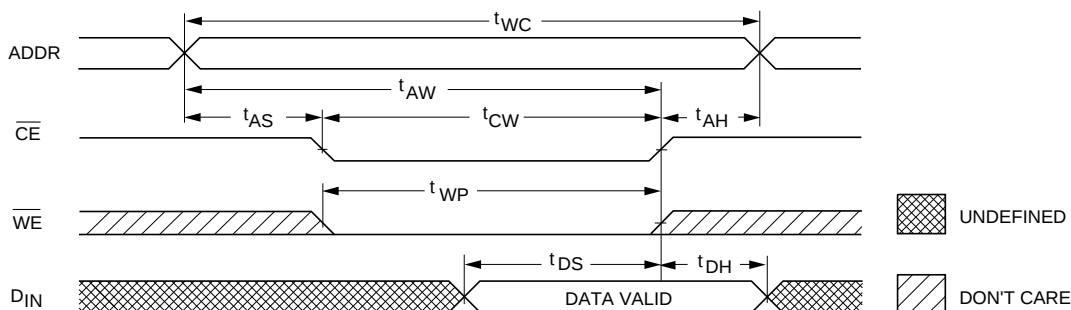


Read Cycle No. 2⁽²⁾



AC Electrical Characteristics

Description		-10		-12		-15		-17		-20		
READ Cycle	Sym	Min.	Max.	Min.	Max.	Min.	Max.	Min	Max	Min	Max	Units
READ cycle time	t_{RC}	10		12		15		17		20		ns
Address access time	t_{AA}		10		12		15		17		20	ns
Chip enable access time	t_{ACE}		10		12		15		17		20	ns
Output hold from address change	t_{OH}	3		3		3		3		3		ns
Chip enable to output in low $Z^{(3,4,5)}$	t_{LZCE}	5		5		5		5		5		ns
Chip disable to output in high $Z^{(3,4,5)}$	t_{HZCE}		8		10		10		12		15	ns
Chip enable to power up time ⁽⁴⁾	t_{PU}	0		0		0		0		0		ns
Chip disable to power down time ⁽⁴⁾	t_{PD}		10		12		15		17		20	ns
Output enable access time	t_{AOE}		5		6		8		9		10	ns
Output enable to output in low $Z^{(4,5)}$	t_{LZOE}	0		0		0		0		0		ns
Output disable to output in high $Z^{(4,5)}$	t_{HZOE}		8		8		8		8		8	ns

Write Cycle No. 1 (Write Enable Controlled)**Write Cycle No. 2 (Chip Enable Controlled)****AC Electrical Characteristics**

Description		-10		-12		-15		-17		-20		
WRITE Cycle	Sym	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
WRITE cycle time	t_{WC}	10		12		15		17		20		ns
Chip enable to end of write	t_{CW}	10		10		12		12		13		ns
Address valid to end of write	t_{AW}	10		10		12		12		13		ns
Address setup time	t_{AS}	0		0		0		0		0		ns
Address hold from end of write	t_{AH}	0		0		0		0		0		ns
Write pulse width	t_{WP}	8		10		11		11		12		ns
Data setup time	t_{DS}	7		7		7		8		9		ns
Data hold time	t_{DH}	0		0		0		0		0		ns
Write disable to output in low Z ^(4,5)	t_{LZWE}	0		0		0		0		0		ns
Write enable to output in high Z ^(4,5)	t_{HZWE}		3		3		3		3		3	ns

NOTES: (For two previous Electrical Characteristics tables)

1. The device is continuously selected. Chip Enable is held in its active state.
2. The address is valid prior to or coincident with the latest occurring Chip Enable.
3. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} .
4. This parameter is sampled.
5. The parameter is tested with $CL = 5$ pF as shown in Figure 2. Transition is measured ± 200 mV from steady state voltage.

Ordering Information

XXXXX Device Type	X Power	XX Speed	X Package Type	X Process Temp. Range	X Preferred Shipping Container	
						Blank Tubes
						TR Tape & Reel
						TY Tray
						Blank Commercial (0° to +70°C)
						I Industrial (-40°C to +85°C)
						A Automotive (-40°C to +105°C)
						SO 28-pin 300-mil Plastic SOJ
						T 28-pin Plastic TSOP (I)
						10 Commercial Only
						12
						15
						17
						20
						SA Standard Power
						PDM31256 - 256K (32Kx8) Sync. Static RAM